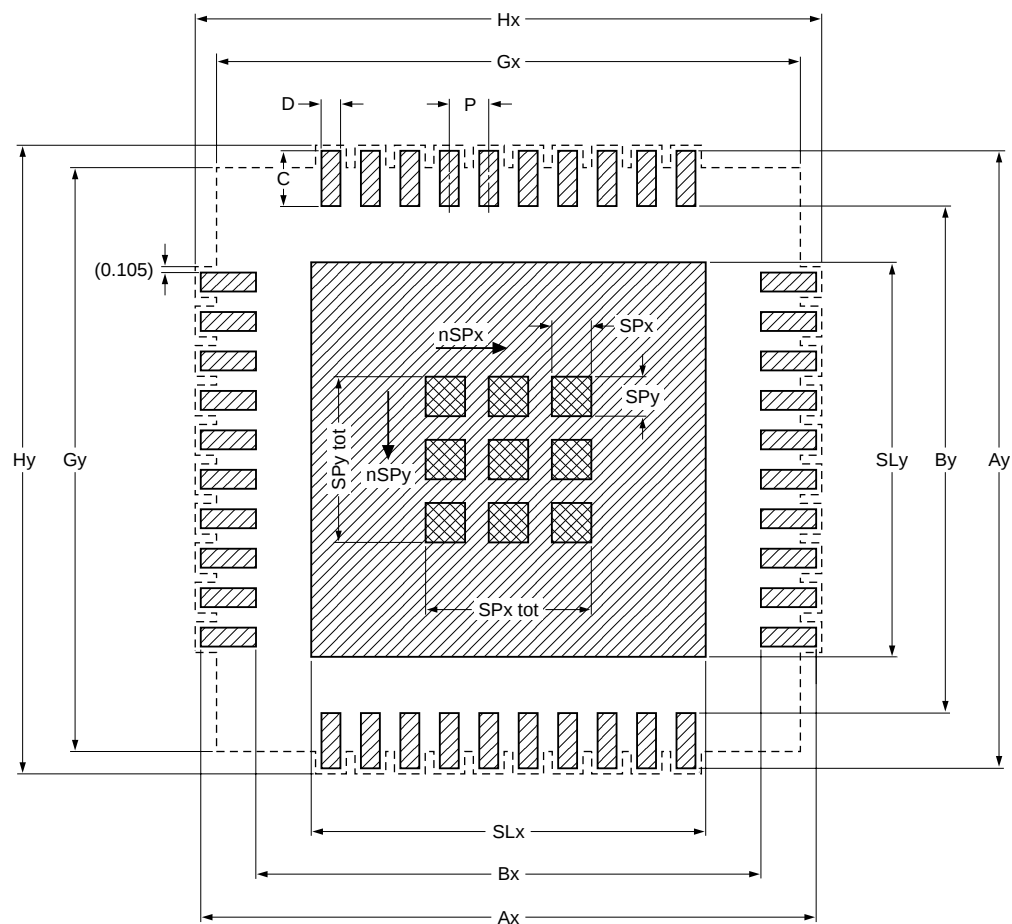


Footprint information for reflow soldering of HVQFN14 package

SOT773-1



Generic footprint pattern

Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area

nSPx	nSPy
1	1

DIMENSIONS in mm

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy
0.500	3.500	3.500	1.900	1.900	0.800	0.240	1.200	1.200	0.550	0.550	0.550	0.550	2.800	2.800	3.750	3.750